Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Currently amended) A method for inspecting semiconductor devices comprising ~~the steps of~~:

setting an inspection ~~conditions~~ condition by using ~~semiconductor device design data~~ chip matrix data and chip size data which are obtained by accessing a design database via communication means;

inspecting a semiconductor ~~devices~~ device with ~~these set~~ said inspection ~~conditions~~ condition;

~~using results of this inspection to revise set~~ revising said inspection ~~conditions~~ condition ~~with said design data~~ by using data obtained by the inspecting; and

inspecting semiconductor devices using ~~these~~ said revised inspection ~~conditions~~ condition.

2. (Currently amended) The method for inspecting semiconductor devices according to claim 1, wherein said inspection condition comprises information ~~that states~~ whether or not an area for inspection is in an area in which false alarms tend to occur ~~is added to inspection conditions set using said design data~~.

3. (Currently amended) The method for inspecting semiconductor devices according to claim 1, wherein said inspection ~~conditions~~ condition ~~set using said design data are~~ is revised during said revising so that only actual foreign matter is detected ~~based on results of a review and classification of defects detected during inspection of said semiconductor devices and so that the percentage of~~ or a false ~~alarms~~ alarm rate is less than ~~or equal to a certain~~ a preset amount.

4. (Currently amended) A method for inspecting semiconductor devices comprising ~~the steps of~~:

specifying a semiconductor ~~devices~~ device product name and names of processes used to process this product and extracting related information from a design data ~~base~~ obtained by accessing a design database via communication means;

setting inspection conditions using ~~this~~ said extracted related information;

inspecting a semiconductor ~~devices~~ device with ~~these~~ said ~~set~~ inspection conditions;

~~using results of this inspection to revise~~ revising said ~~set~~ inspection conditions ~~using said design data~~ by using data obtained during inspecting;

inspecting semiconductor devices using ~~these~~ said revised inspection conditions; and

outputting results of this inspection.

5. (Currently amended) The method for inspecting semiconductor devices according to claim 4, wherein ~~information that states~~ said inspection conditions set at said setting comprises information whether or not an area ~~for inspection~~ to be inspected is in an area in which false alarms tend to occur ~~is added to inspection conditions set using said design data~~.

6. (Currently amended) The method for inspecting semiconductor devices according to claim 4, wherein said inspection conditions set at said setting ~~using said design data~~ are revised at said revising so that only actual foreign matter is detected ~~based on results of a review and classification of defects detected during inspection of said semiconductor devices and so that the percentage of~~ or a false ~~alarms~~ alarm rate is less than ~~or equal to a certain~~ a preset amount.

7. (Currently amended) A method for inspecting semiconductor devices comprising ~~the steps of~~:

setting semiconductor device inspection conditions;

detecting defects by inspecting semiconductor devices using ~~these~~ said set inspection conditions;

classifying ~~these detected~~ defects detected at said detecting by using information from a database obtained by accessing said database via communication means;

revising said set inspection conditions using ~~these~~ classification results; and

inspecting semiconductor devices using ~~these~~ said revised set inspection conditions.

8. (Original) The method for inspecting semiconductor devices according to claim 7, wherein images of said classified defects are displayed on a screen.

9. (Currently amended) The method for inspecting semiconductor devices according to claim 7, wherein, in said ~~step of~~ revising said set inspection conditions, reviewing said classified defects ~~are reviewed,~~ and revising said set inspection conditions ~~are revised~~ by using results of ~~this review~~ said reviewing.

10. (Currently amended) The method for inspecting semiconductor devices according to claim 7, wherein, in said ~~step of~~ setting said set inspection conditions, ~~said~~ semiconductor device design data is used.

11. (New) A method for inspecting semiconductor devices comprising:

setting inspection conditions by using design data obtained by accessing a design database via communication means;

inspecting said semiconductor devices with said inspection conditions;

using results of said inspecting to revise inspection conditions with said design data; and

inspecting said semiconductor devices using said revised inspection conditions,

wherein at least one of said inspection conditions differs by an area inside a chip to be inspected for said semiconductor devices.

12. (New) A method for inspecting semiconductor devices according to claim 11, wherein said inspection conditions comprise defect detection sensitivity, and said defect detection sensitivity differs for the area inside a chip of said semiconductor devices.

13. (New) A method for inspecting semiconductor devices according to the claim 11, wherein said inspection conditions comprise pattern pitch of a special filter which cuts light diffracted from patterns formed on said semiconductor devices and pitches of which differ by the area inside a chip of said semiconductor devices.

14. (New) A method for inspecting a semiconductor device comprising:

receiving an identifier for the semiconductor device;

setting inspection conditions for the semiconductor device using design data obtained by communicating with a design database;

inspecting said semiconductor device for defects with said inspection conditions;

generating revised inspection conditions based on results of said inspecting; and

inspecting said semiconductor device for defects with said revised inspection conditions,

wherein at least one of the inspection conditions is distinctly set for each area of the semiconductor device to be inspected.

15. (New) The method of claim 14 wherein the design database is a physically remote design database.